



SCOPE OF ACCREDITATION

Electronics

Unicircuit

8122 Southpark Lane
Littleton, CO 80120-4519

This certificate expiration is updated based on periodic audits. The current expiration date and scope of accreditation are listed at: www.eAuditNet.com - Online QML (Qualified Manufacturer Listing).

In recognition of the successful completion of the PRI evaluation process, accreditation is granted to this facility to perform the following:

AC7119 Rev G - Nadcap Audit Criteria for Electronics Printed Boards (to be used on audits before 11 March 2018)

- 10– Oxide Coating / Oxide Replacement Coating
- 11– Material Lay–Up and Lamination
- 12.1– Drilling: Mechanical Drilling
- 12.2– Drilling: Laser Drilling– In House
- 12.3– Drilling: Laser Drilling – Out Sourced
- 12.4– Drilling: Post–Drill Cleaning and Etchback
- 13.1– Cooper Plating: Electroless Copper/Direct Metallization
- 13.2– Copper Plating: Electroplated Copper
- 14.1– Final Finishes: Hot Air Solder Leveling (HASL)
- 14.2– Final Finishes: Fused Tin Lead
- 14.3a– Final Finishes: Electroless (Chemical)/Immersion Plating Final Finish – ENIG
- 14.3c– Final Finishes: Electroless (Chemical)/Immersion Plating Final Finish – Immersion Silver
- 14.3d– Final Finishes: Electroless (Chemical)/Immersion Plating Final Finish – Immersion Tin
- 14.3– Final Finishes: Electroless (Chemical)/Immersion Plating Final Finish
- 14.4a– Electroplated Final Finishes: Electroplated Nickel–Gold
- 14.4d– Final Finishes: Electroplated Nickel
- 14.6– Final Finishes: Wire Bondable Plating
- 15– Legend and Marking
- 16– Routing and Machining
- 17– Electrical Test – Functional
- 18– X–Ray Fluorescence (XRF)
- 19– Microsection Sample Selection, Preparation, and Inspection
- 20– Structural Integrity

- 21– Materials Lab
- 22– Chemistry Lab
- 23– Monthly Quality Conformance Testing
- 24– Final Validation
- 25– Packaging
- 6– Engineering Source File Processing
- 7.1– Material Control: General
- 7.2– Material Control: PrePreg
- 8.1– Imaging – Photoprocess
- 8.2.1– DES – Developing Photoimageable Resist
- 8.2.2– DES – Copper Etching of Inner Layers and Outer Layers
- 8.2.3– DES – Stripping of Resist Film and Etch–Resist Plating
- 8.2– Imaging – Develop–Etch–Strip (DES) and Strip–Etch–Strip (SES)
- 8.3– Etched Image Inspection (Manual or AOI)
- 9.1– Permanent Solder Mask: Solder Mask Application
- 9.2– Permanent Solder Mask: Solder Mask Exposing
- 9.3– Permanent Solder Mask: Solder Mask Develop and Cure
- 9– Permanent Solder Mask

AC7119/2 Rev A - Nadcap Audit Criteria for Electronics Flexible and Rigid-Flexible Printed Boards (to be used on audits before 11 March 2018)

- 04– Handling
- 05– Material
- 06– Cover Material Application
- 07– Post–Drill Cleaning and Etchback
- 08– Stiffener Bonding
- 10– Testing
- 11– Depanelization
- 12– Packaging
- 13– Final Validation